

IN THE CLAIMS

Please amend the following claims:

1. (Withdrawn)
2. (Withdrawn)
3. (Withdrawn)
4. (Withdrawn)
5. (Withdrawn)
6. (Withdrawn)
7. (Withdrawn)

AB
Sub B1

8. (Currently amended) A heat spreader for an IC circuit package, comprising:
a thermally conductive heat spreader body having a first surface
configured to thermally couple the heat spreader to an abutting IC die; and
a coating of organic surface protectant on the first surface.

9. (Original) A heat spreader as claimed in claim 8, wherein the body comprises copper.

10. (Currently Amended) A heat spreader as claimed in claim 8, wherein the organic surface protectant comprises one or more imidazole compounds [is applied by dipping or spraying onto the first surface].

11. (Original) A heat spreader as claimed in claim 8, wherein the organic surface protectant comprises one or more triazole compounds or salts thereof.

12. (Original) A heat spreader as claimed in claim 8, wherein the coating completely envelops the body.

13. (Currently amended) An IC package, comprising:
a package substrate;
an IC die attached to the substrate;
a heat spreader body having a first surface thermally coupled to and abutting the IC die; and
a coating of organic surface protectant disposed between the first surface and the IC die.

14. (Original) An IC package as claimed in claim 13, wherein the coating completely envelops the body.

15. (Original) An IC package according to claim 13, further comprising a thermal interface material between the IC die and the coated first surface of the heat spreader.

16. (Original) An IC package according to claim 15, wherein the thermal interface material is a solder or solder-polymer hybrid.

17. (Original) An IC package according to claim 13, wherein the body comprises copper.

18. (Original) An IC package according to claim 13, wherein the organic surface protectant comprises one or more triazole compounds or salts thereof.

19. (Currently amended) An IC package according to claim 13, wherein the first surface is coated with a metal [organic surface protectant is in indirect contact with the first surface].

20. (Currently amended) A printed circuit board assembly comprising:
a printed circuit board,
an IC die electronically coupled to the printed circuit board, and
a heat spreader body having a first surface thermally coupled to and abutting the IC die; and
a coating of organic surface protectant disposed between the first surface and the IC die.

Cont
Sub B1

Copied
#3

Cont
Set B1
Cont
#3

21. (Original) A printed circuit board assembly as claimed in claim 20, further comprising a thermal interface material between the IC die and the coated first surface of the heat spreader, wherein the thermal interface material is a solder or solder-polymer hybrid.
 22. (Original) A printed circuit board assembly as claimed in claim 20, wherein the IC die is directly attached to the printed circuit board.
 23. (Original) A printed circuit board assembly as claimed in claim 20, wherein the IC die is attached to a package substrate that is attached to the printed circuit board.
-